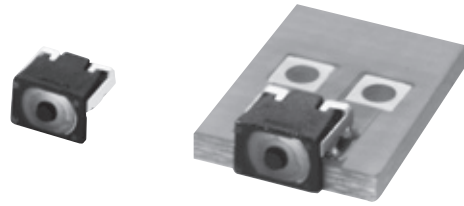


2.8 mm×2.3 mm Side-operational Edge Mount Light Touch Switches

Type: **EVPAV**



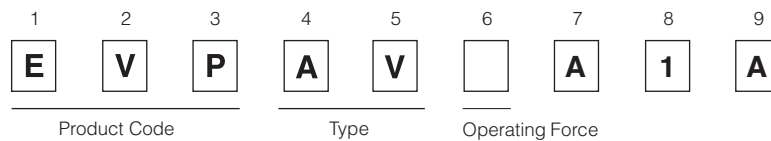
■ Features

- External dimensions : 2.8 mm×2.3 mm (Excluding the push plate), Height 1.95 mm (Printed circuit board being as low as 0.975 mm)
- Improved soldering strength in the operating direction

■ Recommended Applications

- Operation switches for portable electronic equipment (Mobile phones, Digital still cameras, Camcorders Portable audio players, etc.)

■ Explanation of Part Numbers




■ Specifications

Type		Snap action / Push-on type SPST
Electrical	Rating	10 μA 2 V DC to 20 mA 15 V DC (Resistive load)
	Contact Resistance	500 mΩ max.
	Insulation Resistance	50 MΩ min. (at 100 V DC)
	Dielectric Withstanding Voltage	250 V AC for 1 minute
	Bouncing	10 ms max. (ON, OFF)
Mechanical	Operating Force	1.6 N
	Push Travel	0.13 mm
	Push Strength	50 N (15 seconds)
Endurance	Operating Life	300,000 cycles min.
Operating Temperature		-40 °C to +85 °C
Storage Temperature		-40 °C to +85 °C (Bulk) -20 °C to +60 °C (Taping)
Minimum Quantity/Packing Unit		8,000 pcs. Embossed Taping (Reel Pack)
Quantity/Carton		40,000 pcs.

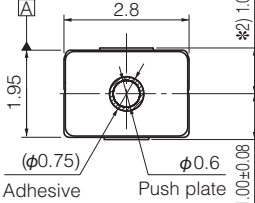
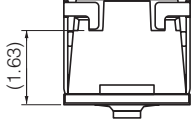
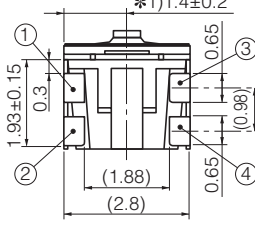
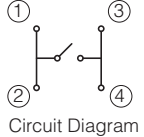
Design and specifications are each subject to change without notice. Ask factory for the current technical specifications before purchase and/or use.
Should a safety concern arise regarding this product, please be sure to contact us immediately.

■ Dimensions in mm (not to scale)

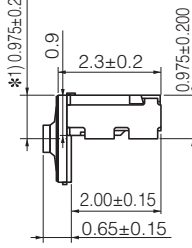
EVPAV



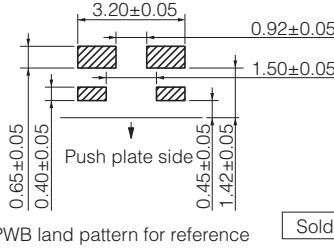
General dimension tolerance : ± 0.1
() dimensions are reference dimensions.

This product is designed to be smaller than the conventional type, which lowered the film peel off strength. Therefore please avoid to apply force to a push plate from side, or/and avoid set-knob to touch push plate during insertion to a set-case.



*1 These dimensions are from the outer shape to the center of push plate.
*2 These dimensions are from the center of datum A.

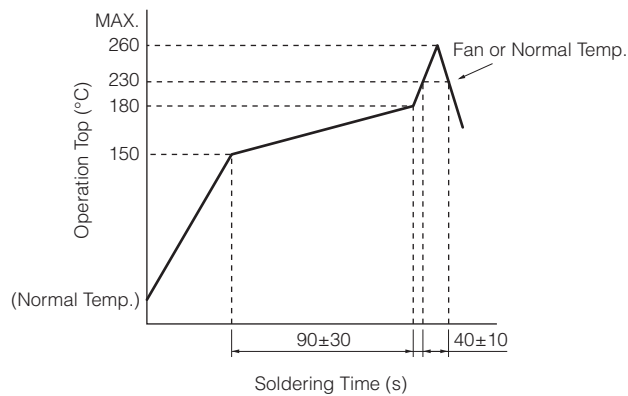


PWB land pattern for reference

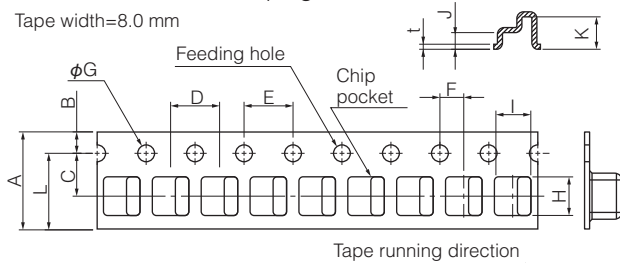
Soldering thickness $t=0.1\pm 0.02$

*Height from surface of PCB : 0.975 mm

■ Recommended Reflow Soldering Conditions



● Embossed Carrier Taping



Taping condition : Lack of products in the middle of taping should be one MAX, but total quantity specified in the specifications should be secured.
Peeling off strength of top tape : It should be within 0.2N to 1.0N at 165 degree in peeling off angle.
Joint of carrier tape : One joint per one reel may exist.

Unit: mm

Part No.	Height	A	B	C	D	E	F	G	H	I	J	K	L	t
EVPAV	1.95	8.0±0.3	1.75±0.10	3.5±0.1	4.0±0.1	4.0±0.1	2.0±0.1	1.5 ^{+0.1} ₋₀	3.1±0.2	2.8±0.2	1.35±0.20	2.7±0.2	(6.25)	0.3±0.1

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单击下面可查看定价，库存，交付和生命周期等信息

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